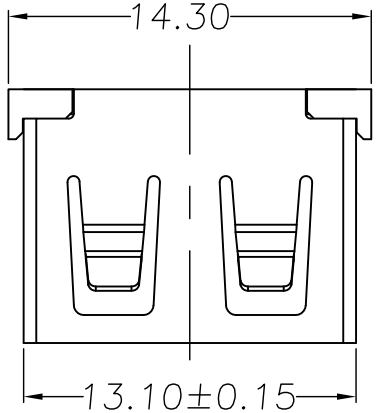
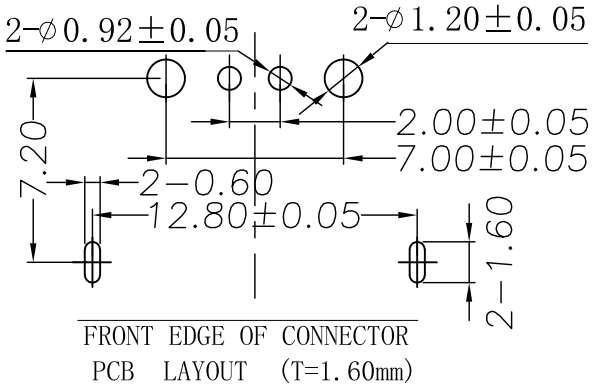
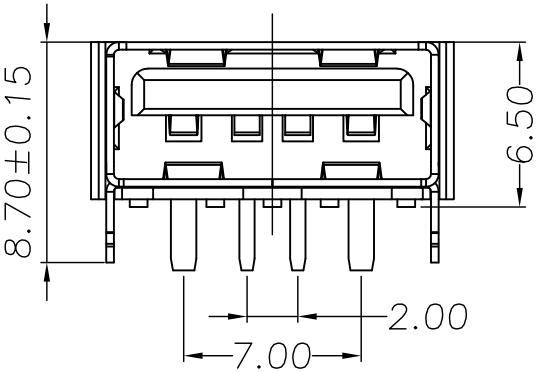
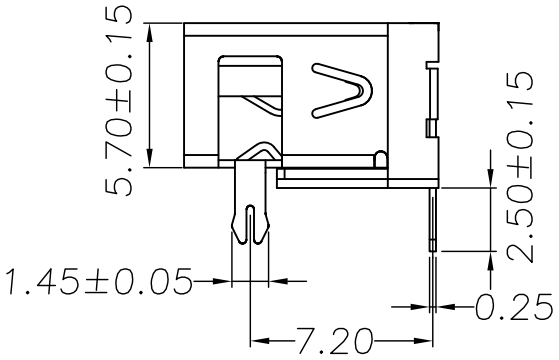
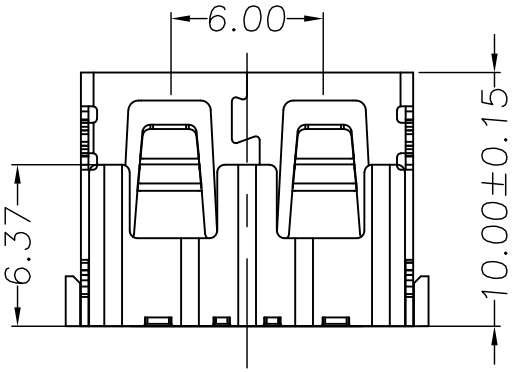
| 更改 REV | 說 明 內 容 MODIFICATION |
|---|---|
| A | ECXXXXX |




Note:

1. Material:
   - 1.1, Housing: High temperature thermoplastic with/black G/F, UL94v-0
   - 1.2, Contact: copper alloy, t=0.25mm
   - 1.3, Shell: copper/Ferroalloy alloy, t=0.30mm
2. Specification:
   - 2.1, Current rating:5A Max.
   - 2.2, Dielectric withstanding voltage: 100 V(ac) for 1 min.
   - 2.3, Contact resistance: 30 mΩ Max.
   - 2.4, Insulation resistance: 100 MΩ Min.
   - 2.5, Total mating force: 3.57 Kgf Max.
   - 2.6, Total unmating force: 1.0 Kgf Min.
3. Finish:
   - 3.1, Contact: Piated Golg in Mating Area: Tin On Solder Talls
     Shell: Nickel Plating
4. Environmental:
   - 4.1, Temperature range: -55° C~85° C

RoHS

| GENERIAL TOLERANCE | | KINGCONN 皇海科技股份有限公司 | | |
|---|---|---|---|---|
| X.± 0.50 | X.°± 5 ° | | | |
| .X± 0.30 | .X°± 2 ° | | | |
| .XX± 0.20 | .XX°± 1 ° | 名 稱(TITLE) USB2.0 AF 10.0 H:6.5mm無卷邊大電流 | | |
| 單 位(UNIT) mm | 料 號(PART NO.) 7USB2-F0-A002 | | 圖 號(DWG NO.) 7USB2-F0-A002 | |
| 審 核(APPROVAL) | 核 對(CHECKED) | 製 圖(DRAWN) | 比例 SCALE 1:1 | 張數 SHEET 1/1 |
| | | | 單位 PROJ. | 更改 REV A |

QP-701-03-R